

## REMARKS CONCERNING REVISED FIGURES

Appendix A includes revised drawing sheets 1 – 5, and 9 – 10.

Revised drawing sheets 1 – 5 and 10 have corrected the solder resist 6 layer to be flush with the sealing epoxy resin 5. Support for this revision may be found in the originally filed figures of Application Serial No. 09/487,682 filed January 19, 2000 now U.S. Patent No. 6,365,432 issued April 2, 2002, which is the parent of the above-identified application. Therefore no new matter has been added by the revision.

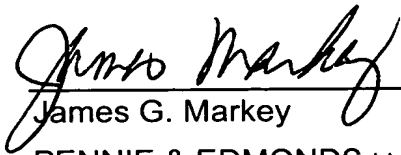
Revised drawing sheet 9 has been revised to correct the hatching pattern for the copper foil 1 in Fig. 9c. The hatching pattern for copper foil 1 in Fig. 9c is not the same hatching pattern as in Figs. 9a and 9b, but is erroneously the hatching pattern for sealing resin 17 in Figs. 9e and 9f. Support for this revision may be found in the originally filed figures of Application Serial No. 09/487,682 filed January 19, 2000 now U.S. Patent No. 6,365,432 issued April 2, 2002, which is the parent of the above-identified application. Therefore no new matter has been added by the revision.

Applicants respectfully request entry of the foregoing amendments and remarks into the file history of the above-identified application. An early allowance of the application is earnestly requested. The Examiner is invited to contact Steven Fukuda at 212.790.6524 with any questions concerning the foregoing.

No fee is believed to be due for this submission. Should any fees be required, however, please charge such fees to Pennie & Edmonds Deposit Account No. 16-1150.

Respectfully submitted,

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